

Thyristor

 $V_{RRM} = 1600 V$

 $I_{TAY} = 80 A$

 $V_T = 1.27 V$

Single Thyristor

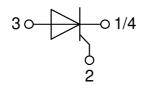
Part number

MCO75-16io1



Backside: isolated





Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper
- internally DCB isolated

 Advanced power cycling

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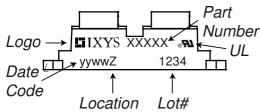
Thyristo					Ratings	1	
Symbol	Definition	Conditions	T 0500	min.	typ.	max.	Un
V _{RSM/DSM}	max. non-repetitive reverse/forwa		$T_{VJ} = 25^{\circ}C$			1700	1
V _{RRM/DRM}	max. repetitive reverse/forward bloom		$T_{VJ} = 25^{\circ}C$			1600	! '
I _{R/D}	reverse current, drain current	$V_{R/D} = 1600 \text{ V}$	$T_{VJ} = 25^{\circ}C$			50	μ
		$V_{R/D} = 1600 \text{ V}$	$T_{VJ} = 125^{\circ}C$			10	m
V _T	forward voltage drop	$I_T = 75 A$	$T_{VJ} = 25^{\circ}C$			1.28	'
		I _⊤ = 150 A				1.60	<u> </u>
		$I_{T} = 75 A$	$T_{VJ} = 125$ °C			1.27	,
		$I_{T} = 150 \text{ A}$				1.67	,
I _{TAV}	average forward current	$T_C = 80^{\circ}C$	$T_{VJ} = 150$ °C			80	
I _{T(RMS)}	RMS forward current	180° sine				125	
V _{T0}	threshold voltage		T _{vJ} = 150°C			0.85	١
r _T	slope resistance } for power lo	oss calculation only				5.5	m۵
R _{thJC}	thermal resistance junction to cas	e				0.45	K/V
R _{thCH}	thermal resistance case to heatsin	nk			0.1		K/V
P _{tot}	total power dissipation		T _C = 25°C			270	٧
I _{TSM}	max. forward surge current	t = 10 ms; (50 Hz), sine	T _{v.i} = 45°C			1.07	k/
TOW	-	t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			1.16	k,
		t = 10 ms; (50 Hz), sine	T _{v.i} = 150°C			910	,
		t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			980	
l²t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			5.73	1
	value iei iueilig	t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			5.55	i
		t = 0.5 ms; (50 Hz), sine t = 10 ms; (50 Hz), sine	$T_{VJ} = 150^{\circ}C$			4.14	1
		t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			4.00	į
<u> </u>	junction capacitance	$V_R = 400 \text{ V} \text{ f} = 1 \text{ MHz}$	$V_R = 0 V$ $T_{VJ} = 25^{\circ}C$		54	4.00	
C _J			$T_{VJ} = 25 \text{ C}$ $T_{C} = 150 \text{ °C}$		54	10	pl V
P_{GM}	max. gate power dissipation	$t_{P} = 30 \mu s$	1 _C = 150 C				į
_		$t_{P} = 300 \mu s$				5	۷
P _{GAV}	average gate power dissipation					0.5	۷
(di/dt) _{cr}	critical rate of rise of current	$T_{VJ} = 150 ^{\circ}\text{C}; f = 50 \text{Hz}$ re	•			150	A/μ
		$t_P = 200 \mu s; di_G/dt = 0.3 A/\mu s; -$					<u> </u>
			on-repet., $I_T = 75 A$				A/μ:
(dv/dt) _{cr}	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150$ °C			1000	V/µ
		R _{GK} = ∞; method 1 (linear volta					1 1 1
V_{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			1.5	١
			$T_{VJ} = -40$ °C			1.6	١
I _{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			100	m/
			$T_{VJ} = -40$ °C			200	m/
V _{GD}	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	T _{VJ} = 150°C			0.2	١
I _{GD}	gate non-trigger current					10	m/
I _L	latching current	t _p = 10 μs	$T_{VJ} = 25 ^{\circ}C$			450	m
		$I_{G} = 0.3 \text{ A}; \text{ di}_{G}/\text{dt} = 0.3 \text{ A}/\mu\text{s}$: ! ! !
I _H	holding current	$V_D = 6 \text{ V } R_{GK} = \infty$	$T_{VJ} = 25$ °C			200	m
·н t _{gd}	gate controlled delay time	$V_{D} = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25 ^{\circ}\text{C}$			2	μ
-ga	gant time and anaj amo	$I_{\rm G} = 0.3 \text{A}; \text{di}_{\rm G}/\text{dt} = 0.3 \text{A}/\mu \text{s}$				_	μ
					ļ		
t _q	turn-off time	$V_R = 100 \text{ V}; I_T = 75\text{A}; V = \frac{2}{3}$	(a \/ _10k or		150		μ



Package	Package SOT-227B (minibloc)				Ratings				
Symbol	Definition	Conditions			min.	typ.	max.	Unit	
I _{RMS}	RMS current	per terminal 10					150	Α	
T _{VJ}	virtual junction temperatur	re			-40		150	°C	
T _{op}	operation temperature				-40		125	°C	
T _{stg}	storage temperature				-40		150	°C	
Weight						30		g	
M _D	mounting torque				1.1		1.5	Nm	
$\mathbf{M}_{_{T}}$	terminal torque				1.1		1.5	Nm	
d _{Spp/App}	oroonaga diatanaa an aurt	face Latriking diatance through air	terminal to terminal	10.5	3.2			mm	
$d_{Spb/Apb}$	creepage distance on sun	face striking distance through air	terminal to backside	8.6	6.8			mm	
V _{ISOL}	isolation voltage	t = 1 second	50/60 Hz, RMS; lisoL ≤ 1 mA		3000			٧	
1002		t = 1 minute			2500			٧	

¹⁾ I_{hus} is typically limited by the pin-to-chip resistance (1); or by the current capability of the chip (2). In case of (1) and a product with multiple pins for one chip-potential, the current capability can be increased by connecting the pins as one contact.



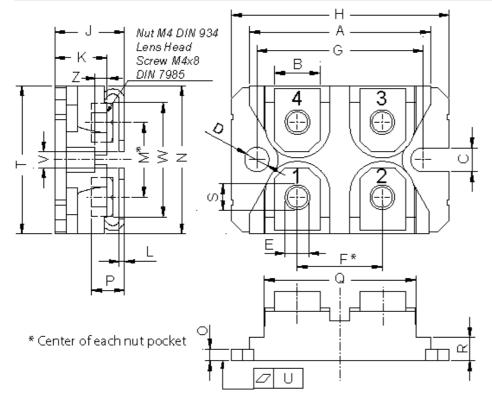


Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCO75-16io1	MCO75-16io1	Tube	10	505811

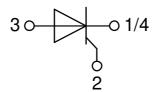
Equivalent Circuits for Simulation			* on die level	$T_{VJ} = 150$ °C
$I \rightarrow V_0$)— <u>R</u> o	Thyristor		
V _{0 max}	threshold voltage	0.85		V
R _{0 max}	slope resistance *	3.4		mΩ



Outlines SOT-227B (minibloc)



Dim.	Millir	neter	Inches			
DIIII.	min	max	min	max		
Α	31.50	31.88	1.240	1.255		
В	7.80	8.20	0.307	0.323		
С	4.09	4.29	0.161	0.169		
D	4.09	4.29	0.161	0.169		
Е	4.09	4.29	0.161	0.169		
F	14.91	15.11	0.587	0.595		
G	30.12	30.30	1.186	1.193		
Н	37.80	38.23	1.488	1.505		
J	11.68	12.22	0.460	0.481		
Κ	8.92	9.60	0.351	0.378		
L	0.74	0.84	0.029	0.033		
M	12.50	13.10	0.492	0.516		
N	25.15	25.42	0.990	1.001		
0	1.95	2.13	0.077	0.084		
Р	4.95	6.20	0.195	0.244		
Q	26.54	26.90	1.045	1.059		
R	3.94	4.42	0.155	0.167		
S	4.55	4.85	0.179	0.191		
Т	24.59	25.25	0.968	0.994		
U	-0.05	0.10	-0.002	0.004		
V	3.20	5.50	0.126	0.217		
W	19.81	21.08	0.780	0.830		
Ζ	2.50	2.70	0.098	0.106		





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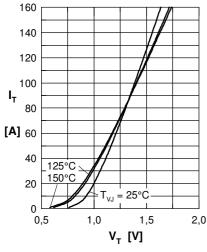


Fig. 1 Forward characteristics

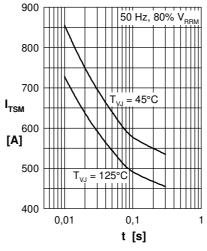


Fig. 2 Surge overload current

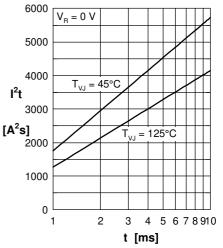


Fig. 3 I²t versus time (1-10 ms)

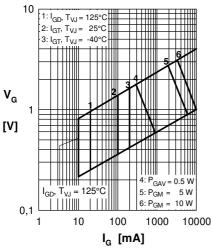


Fig. 4 Gate trigger characteristics

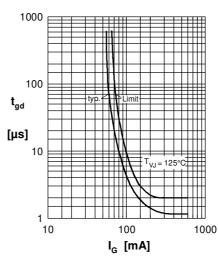


Fig. 5 Gate controlled delay time

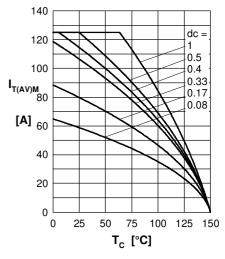


Fig. 6 Max. forward current at case temperature

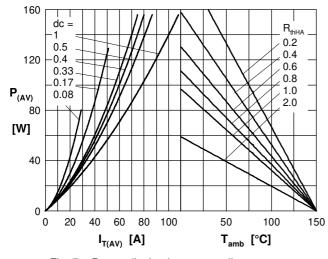


Fig. 7a Power dissipation versus direct output current Fig. 7b and ambient temperature

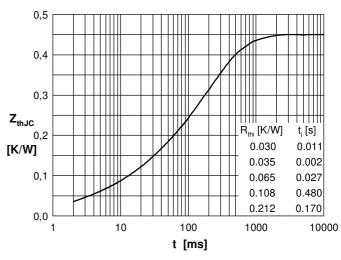


Fig. 8 Transient thermal impedance junction to case

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<u>25.163.2453.0</u> <u>25.16</u>	63.4253.0 25.	190.2053.0	25.194.3453.0	25.320.4853.1	25.320.5253.1	25.326.3253.1	25.326.3553.1	25.330.1653.1
<u>25.330.4753.1</u> <u>25.33</u>	30.5253.1 25.	334.3253.1	25.334.3353.1	25.350.2053.0	25.352.4753.1	25.522.3253.0	<u>T483C</u> <u>T484C</u>	<u>T485F</u> <u>T485H</u>
T512F-YEB T513F	T514F T554	<u>T612FSE</u>	25.161.3453.0	25.179.2253.0	25.194.3253.0	25.325.1253.1	25.326.4253.1	25.330.0953.1
<u>25.332.4353.1</u> <u>25.35</u>	50.1653.0 25.	350.2453.0	25.352.1453.0	25.352.1653.0	25.352.2453.0	25.352.5453.1	25.522.3353.0	25.602.4053.0
25.640.5053.0								